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N-Channel 100 V (D-S) Super Junction MOSFET

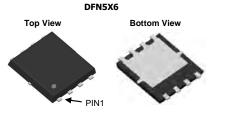
| PRODUCT SUMMARY | | | | | | |
|---------------------|--------------------------------|---------------------------------|-----------------------|--|--|--|
| V _{DS} (V) | R _{DS(on)} (mΩ)(Typ.) | I _D (A) ^a | Q _g (Typ.) | | | |
| 100 | 6.3 at V _{GS} = 10 V | 105 | 37 nC | | | |

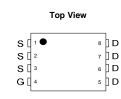
FEATURES

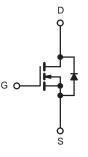
- **DT-SJ Power MOSFET**
- Very low on-resistance
- 100 % Rg and UIS Tested
- Fast switching •

APPLICATIONS

- Power Management
- Motor Drivers ٠
- **DC-DC** Converters ٠







N-Channel MOSFET

| ORDERING INFORMATION | | | | | | |
|----------------------|--------------|------|-----------|-----|----------|--|
| Part Number | Package Type | Form | # of Pins | MSL | Qty(pcs) | |
| DTQ6080N10SJ | DFN5X6-8L | Reel | 8 | 3 | 5000 | |

| ABSOLUTE MAXIMUM RATINGS | S (T _A = 25 °C, unle | ess otherwise no | oted) | |
|--|--|------------------|----------------------|----|
| Parameter | Symbol | Limit | Unit | |
| Drain-Source Voltage | V _{DS} | 100 | V | |
| Gate-Source Voltage | | V _{GS} | | |
| Continuous Drain Current (T ₁ = 150 °C) | T _C = 25 °C | 1 | 105 | |
| Continuous Drain Current $(1) = 150^{\circ}$ C) | T _C = 100 °C | I _D | 65 | A |
| Pulsed Drain Current (t = 300 µs) | | I _{DM} | 400 | |
| Single Pulse Avalanche Current | L = 0.1 mH | I _{AS} | 64 | |
| ingle Pulse Avalanche Energy | | E _{AS} | 205 | mJ |
| | T _C = 25 °C | | 125 | |
| Maximum Power Dissipation | T _C = 100 °C | PD | 80 | w |
| | T _A = 25 °C | ' D | 2.1 ^{b, c} | |
| | T _A = 100 °C | | 2.84 ^{b, c} | |
| Operating Junction and Storage Temperature Ra | T _J , T _{stg} | -55 to 150 | つ ∘ | |
| Soldering Recommendations (Peak Temperature | | 260 | Ŭ | |

| THERMAL RESISTANCE RATINGS | | | | | | |
|---|--------------|-------------------|---------|---------|------|--|
| Parameter | | Symbol | Typical | Maximum | Unit | |
| Maximum Junction-to-Ambient ^{b, f} | t ≤ 10 s | R _{thJA} | 40 | 60 | °C/W | |
| Maximum Junction-to-Case (Drain) | Steady State | R _{thJC} | 0.8 | 1 | 0/11 | |

Notes:

a. Based on T_C = 25 °C.
b. Surface mounted on 1" x 1" FR4 board.

c. t = 10 s.

- d. The DFN5X6 is a leadless package. The end of the lead terminal is exposed copper
- (not plated) as a result of the singulation process in manufacturing. A solder fillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side solder interconnection.
- e. Rework conditions: manual soldering with a soldering iron is not recommended for leadless components.

f. Maximum under steady state conditions is 70 °C/W.



COMPLIANT

| PARAMETER | SYMBOL | TEST CONDITIONS | MIN. | TYP. | MAX. | UNIT | |
|---|---------------------|--|------|------|-------|------|--|
| Static | | | | | | | |
| Drain-Source Breakdown Voltage | V _{DS} | V_{DS} $V_{GS} = 0 V$, $I_D = 250 \mu A$ | | - | - | V | |
| Gate Threshold Voltage | V _{GS(th)} | $V_{DS}=V_{GS},\ I_{D}=250\ \mu A$ | 1 | - | 3 | v | |
| Gate-Body Leakage | I _{GSS} | V_{DS} = 0 V, V_{GS} = ± 20 V | - | - | ± 100 | nA | |
| | | $V_{DS} = 100 \text{ V}, \text{ V}_{GS} = 0 \text{ V}$ | - | - | 1 | | |
| Zero Gate Voltage Drain Current | I _{DSS} | $V_{DS} = 80 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 85 ^{\circ}\text{C}$ | | - | 10 | μA | |
| On-State Drain Current ^a | I _{D(on)} | $V_{DS} \geq 10~V,~V_{GS} = 10~V$ | 105 | - | - | А | |
| Drain-Source On-State Resistance ^a | R _{DS(on)} | $V_{GS} = 10 \text{ V}, \text{ I}_{D} = 15 \text{ A}$ | - | 6.3 | 8.0 | mΩ | |
| Forward Transconductance ^a | g _{fs} | V _{DS} = 10 V, I _D = 15 A | | 65 | - | S | |
| Dynamic ^b | | | - | • | • | | |
| Input Capacitance | C _{iss} | | - | 1880 | - | pF | |
| Output Capacitance | C _{oss} | V_{GS} = 0 V, V_{DS} = 50 V, f = 1MHz | - | 931 | - | | |
| Reverse Transfer Capacitance | C _{rss} | | - | 21 | - | | |
| Total Gate Charge ^c | Qg | | - | 37 | - | nC | |
| Gate-Source Charge ^c | Q _{gs} | $V_{DS} = 50 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 15 \text{ A}$ | - | 4.2 | - | | |
| Gate-Drain Charge ^c | Q _{gd} | | - | 8.5 | - | | |
| Gate Resistance | R _g | f = 1 MHz | - | 2 | - | Ω | |
| Turn-On Delay Time ^c | t _{d(on)} | | - | 15 | - | – ns | |
| Rise Time ^c | t _r | $V_{DD} = 50 \text{ V}, \text{ R}_{g} = 6 \Omega$ | - | 33 | - | | |
| Turn-Off Delay Time ^c | t _{d(off)} | $I_{\rm D} = 15$ A, $V_{\rm GEN} = 10$ V, | - | 61 | - | | |
| Fall Time ^c | t _f | | - | 28 | - | 1 | |
| Drain-Source Body Diode Ratings and | nd Characteris | stics ^b (T _C = 25 °C) | · | | · | | |
| Continuous Source Current | I _S | T _C = 25 °C | - | - | 105 | А | |
| Pulsed Source Current | I _{SM} | | - | - | 400 | А | |
| Forward Voltage ^a | V _{SD} | $I_F = 1 \text{ A}, V_{GS} = 0 \text{ V}$ | - | - | 1 | V | |
| Reverse Recovery Time | t _{rr} | L = 15 A di/dt = 100 A/··· | - | 220 | - | ns | |
| Reverse Recovery Charge | Q _{rr} | I _F = 15 A, di/dt = 100 A/μs | - | 480 | - | nC | |

Notes

a. Pulse test; pulse width $\leq 300~\mu\text{s},~\text{duty}~\text{cycle} \leq 2~\%.$

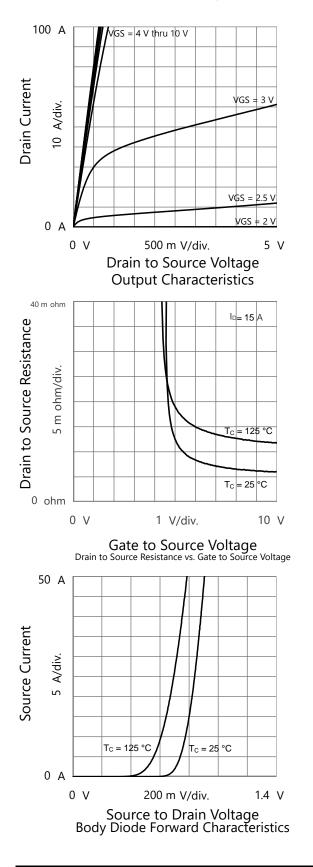
b. Guaranteed by design, not subject to production testing.

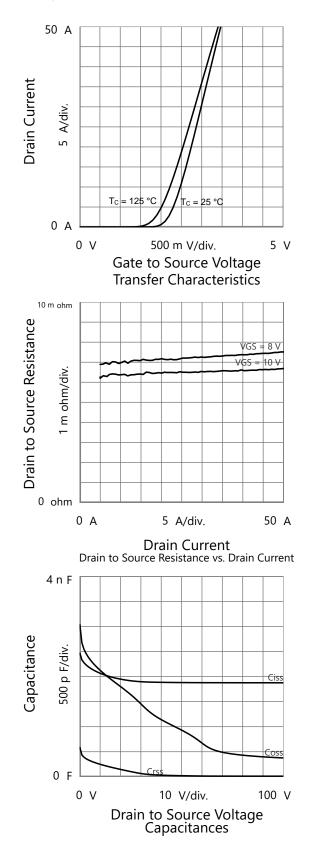
c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



TYPICAL CHARACTERISTICS (T_A = 25 °C, unless otherwise noted)

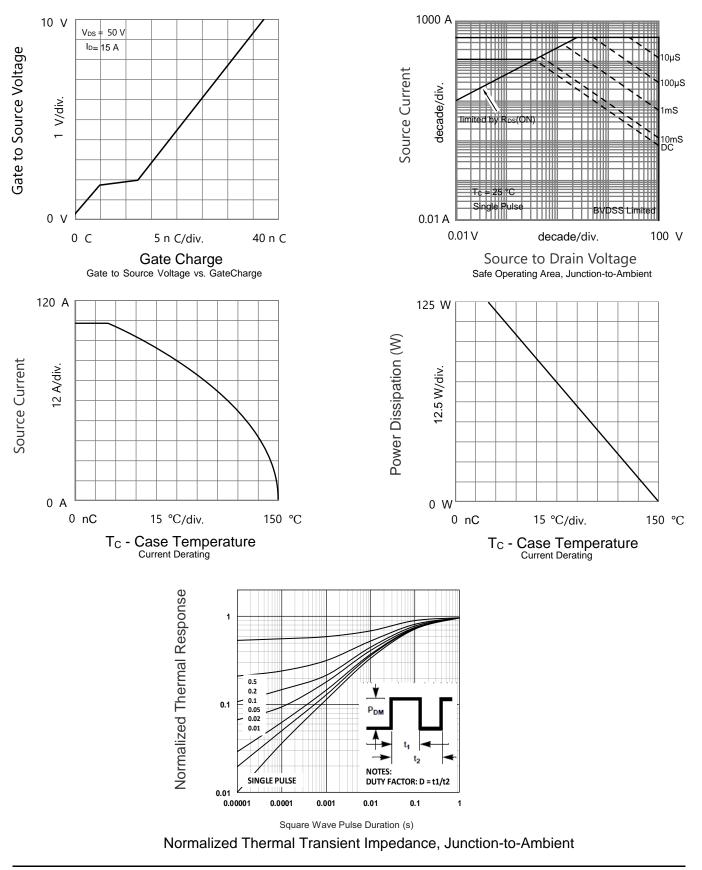






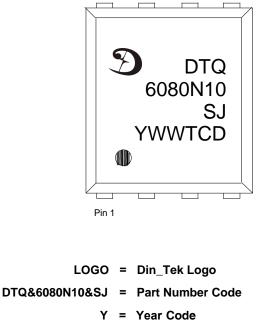
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TYPICAL CHARACTERISTICS (T_A = 25 °C, unless otherwise noted)





Mark:



- WW = Week Code
- TCD = Tracking Code

NOTES:

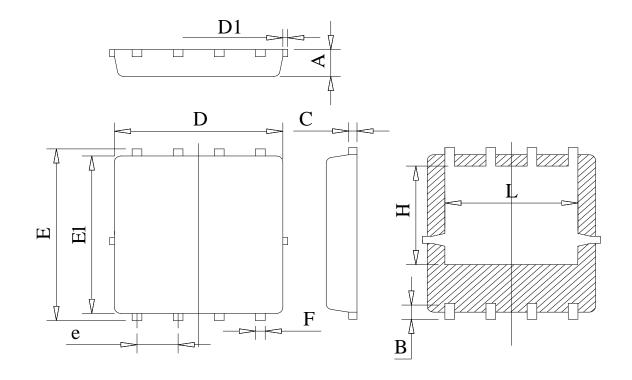
- Year Code : M = 2022, N = 2023, P = 2024, ... The easily confused letter "O" does not participate in sorting
- 2. Week Code : Week1 = 01, Week2 = 02, Week3 = 03, \dots

The current marking strategy is reflected. Contact your local sales representative for historical marking strategies for hese packages.



DFN5*6-8L PACKAGE OUTLINE

Din-Tek SEMICONDUCTOR



COMMON DIMENSIONS (UNITS OF MEASURE=MILLIMETER)

| Unit : mm | | | |
|-----------|------|-------|------|
| Symbol | Min | Тур | Max |
| A | 0.78 | 0.95 | 1.12 |
| В | 0.45 | 0.58 | 0.78 |
| С | 0.18 | 0.254 | 0.36 |
| D | 4.70 | 5.20 | 5.45 |
| D1 | | | 0.18 |
| E | 5.85 | 6.05 | 6.25 |
| E1 | 5.38 | 5.55 | 5.98 |
| e | 1.15 | 1.27 | 1.40 |
| F | 0.18 | 0.30 | 0.52 |
| Н | 3.25 | 3.47 | 3.70 |
| L | 3.75 | 4.00 | 4.25 |



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